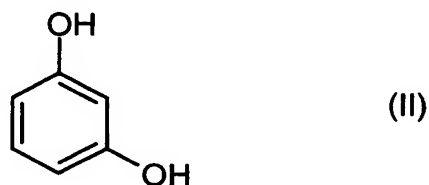
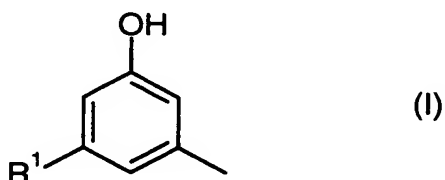


Claims

1. A two-component epoxy resin composition, characterized in that it comprises in the hardener component at least one Mannich base and after curing at a temperature between 5°C and 60°C has a glass transition temperature of more than 80°C.
2. The two-component epoxy resin composition as claimed in claim 1, characterized in that the Mannich base is prepared using a phenolic compound of the formula (I) or (II)



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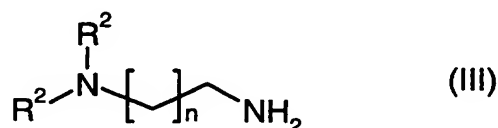
with $R^1 = H$ or CH_3 ,

and also formaldehyde and at least one polyamine.

3. The two-component epoxy resin composition as claimed in claim 1 or claim 2, characterized in that the Mannich base is prepared using a phenolic compound of the formula (I) with $R^1 = H$.
4. The two-component epoxy resin composition as claimed in any one of the preceding claims, characterized in that, for the preparation of the Mannich base, in a first stage at least one phenolic compound of the formula (I) or (II) is reacted with formaldehyde in the presence of a tertiary amine and in a subsequent stage reaction takes place with at least one polyamine.

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5. The two-component epoxy resin composition as claimed in claim 4, characterized in that the tertiary amine has the formula (III)



with $\text{R}^2 = \text{C}_1\text{-C}_6$ alkyl and $n = 1, 2, \text{ or } 3$.

- 5 6. The two-component epoxy resin composition as claimed in any one of the preceding claims, characterized in that the Mannich base contains not only secondary but also primary amino groups.
7. The two-component epoxy resin composition as claimed in any one of the preceding claims, characterized in that the polyamines selected from the group encompassing DAMP, IPDA, 1,3- and 1,4-diaminocyclohexane, 1,2-diaminocyclohexane 1,3- and 1,4-butanediamine, 1,3- and 1,5-pentanediamine, MPMD, 1,3-xylylenediamine, 1,3-bis(amino-methyl)cyclohexane, diethylenetriamine, triethylenetetramine (3,6-diaza-octamethylenediamine), tetraethylenepentamine, pentamethylene-hexamine, dipropylenetriamine, tripropylenetetramine, tetrapropylene-pentamine, 4,7-diaza-decamethylene-1,10-diamine, bis(4-aminocyclo-hexyl)methane, bis(4-amino-3-methylcyclohexyl)methane, 3(4),8(9)bis-(aminomethyl)tricyclo[5.2.1.0^{2,6}]decane, and mixtures thereof.
8. The two-component epoxy resin composition as claimed in any one of the preceding claims, characterized in that the polyamine is selected from the group encompassing 1,3-xylylenediamine, 1,3-bis(aminomethyl)-cyclohexane, diethylenetriamine, triethylenetetramine (3,6-diazaocta-methylenediamine), tetraethylenepentamine, IPDA, 1,2-diamino-cyclohexane, 4,7-diaza-decamethylene-1,10-diamine, and mixtures thereof.
9. The two-component epoxy resin composition as claimed in any one of the preceding claims, characterized in that curing takes place at a

temperature between 10°C and 50°C, in particular between 10°C and 30°C.

- 5 10. The two-component epoxy resin composition as claimed in any one of the preceding claims, characterized in that, after curing, the glass transition temperature is above 100°C, in particular between 100°C and 150°C.
11. The use of a two-component epoxy resin composition as claimed in any one of claims 1 to 10 as an adhesive.
- 10 12. The use of a two-component epoxy resin composition as claimed in claim 11, characterized in that the adhesive is used for structural reinforcement.
- 15 13. The use of a two-component epoxy resin composition as claimed in claim 12, characterized in that the adhesive is used for bonding fiber-reinforced composites to built structures.
- 20 14. The use of a two-component epoxy resin composition as claimed in any one of claims 1 to 10 as a polymeric matrix for producing fiber-reinforced composites.
- 25 15. A fiber-reinforced composite, characterized in that it is produced using a two-component epoxy resin composition as claimed in any one of claims 1 to 10.
- 30 16. A method of adhesive bonding, characterized in that a two-component epoxy resin composition as claimed in any one of claims 1 to 10 is mounted to at least one solid's surface and subsequently contacted with at least one further solid's surface.
17. A cured product obtained from a two-component epoxy resin composition as claimed in any one of claims 1 to 10.